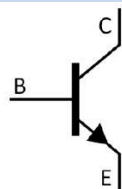


/ Descriptions

/ Features

/ Applications

/ Equivalent Circuit



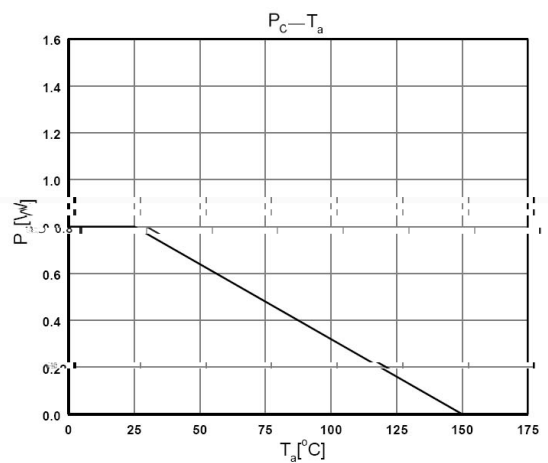
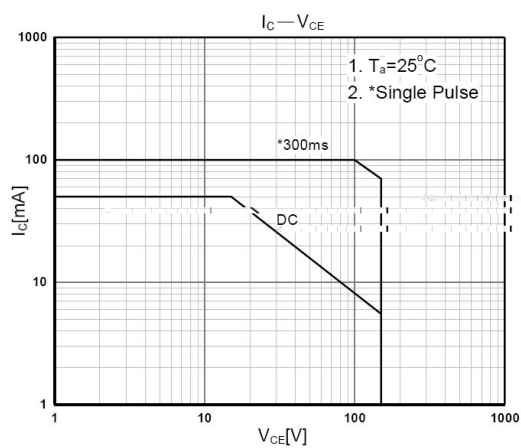
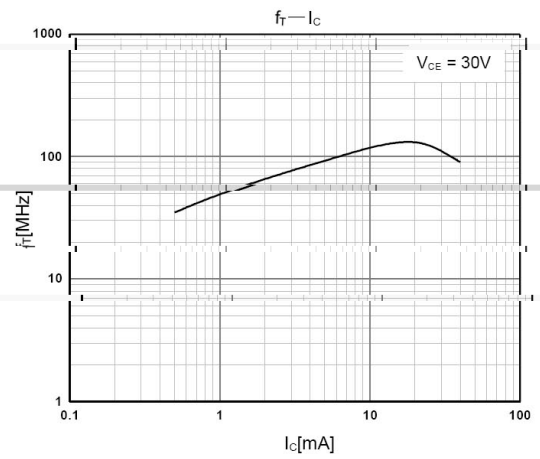
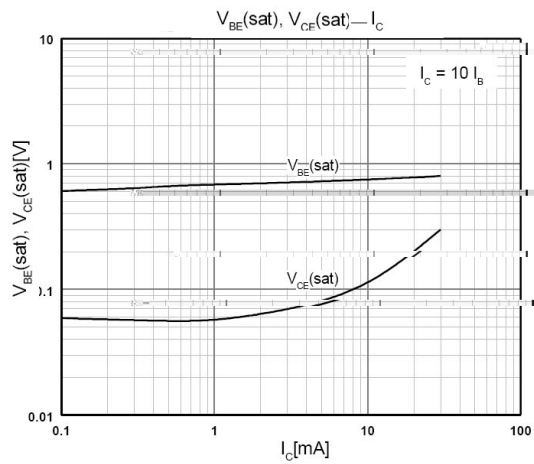
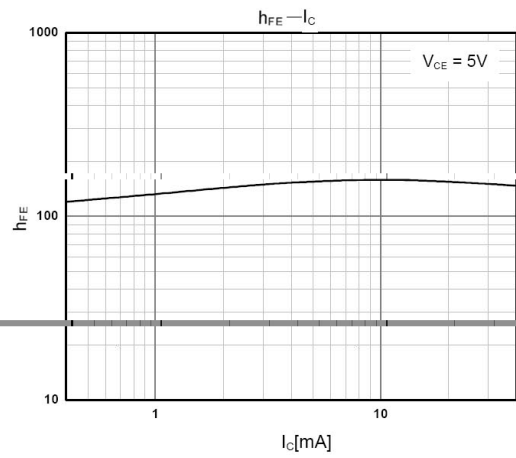
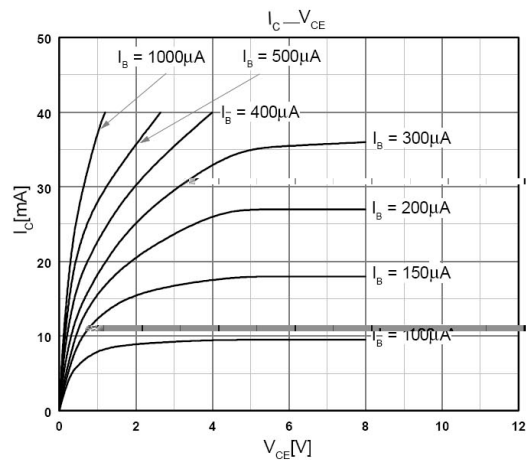
/ Pinning



/ h_{FE} Classifications & Marking

		μ				
		μ				
						μ

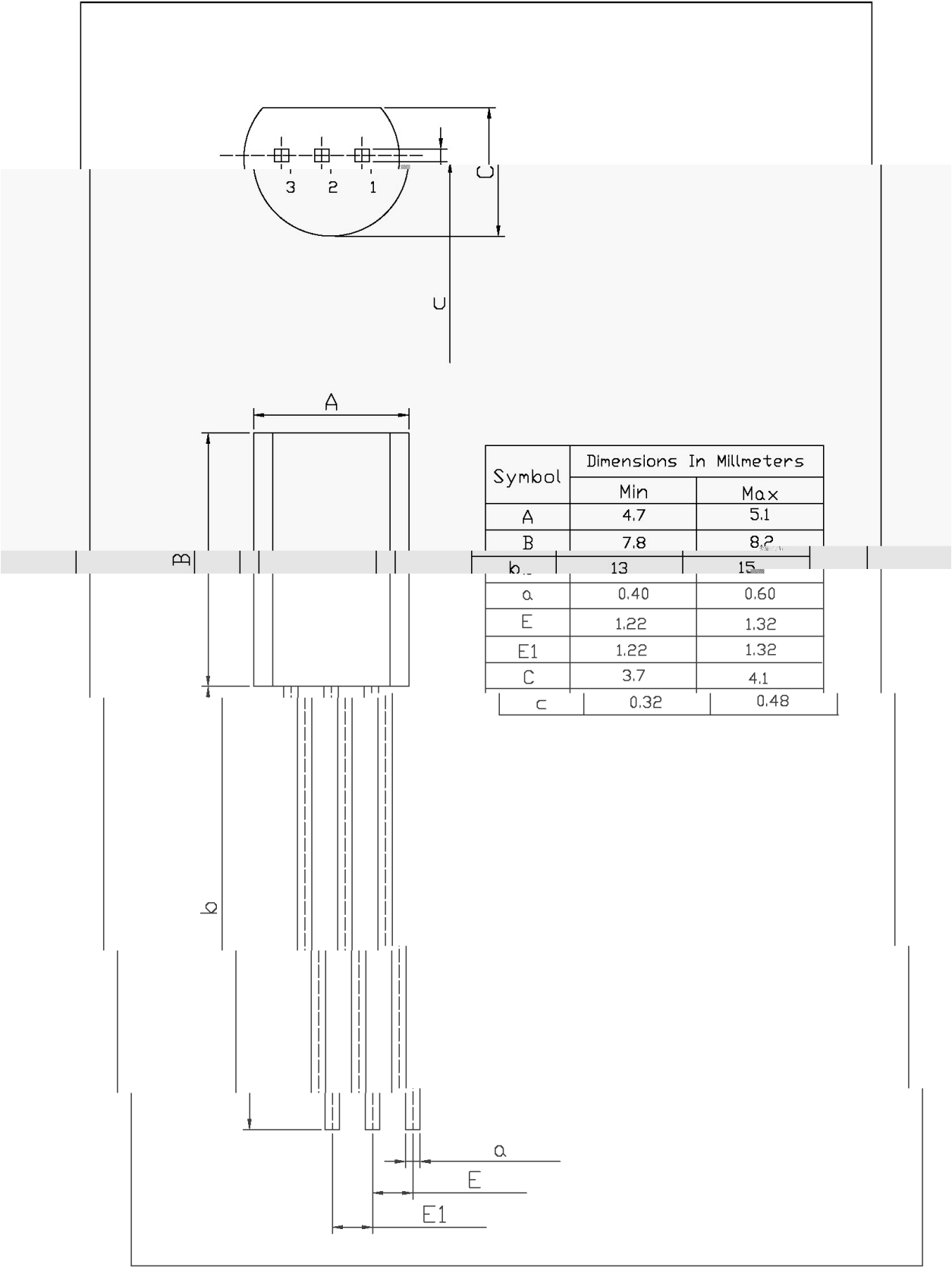
/ Electrical Characteristic Curve



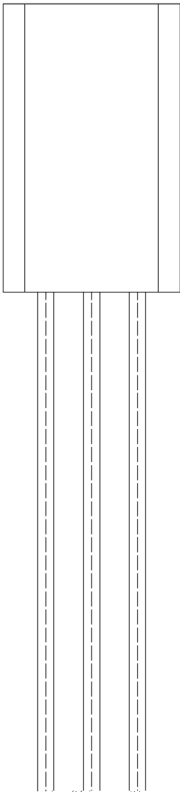
/ Package Dimensions

T0-92LM

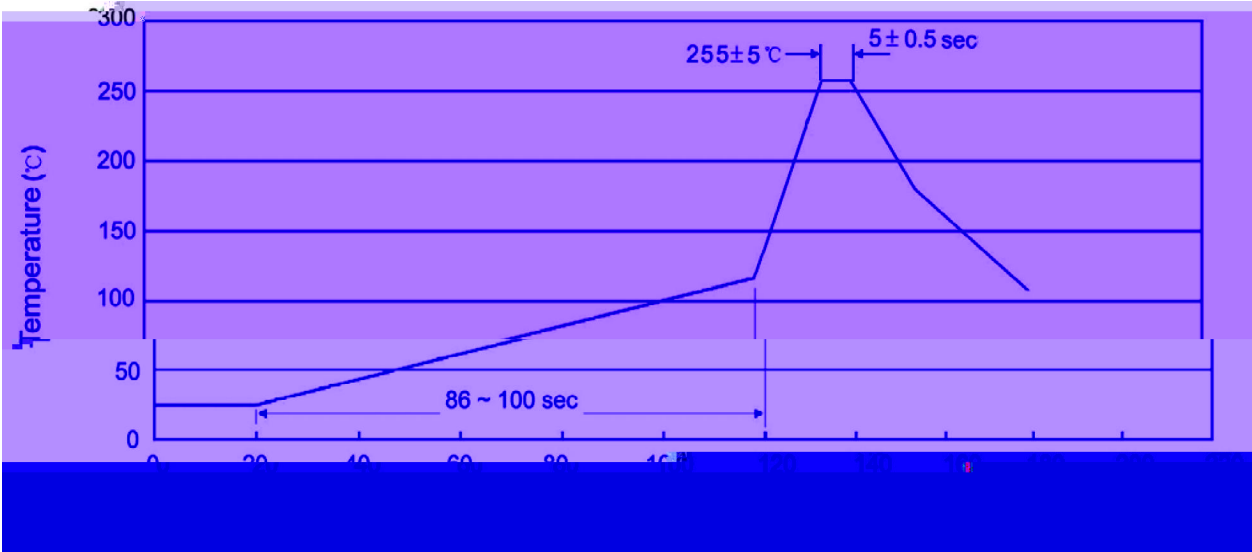
Unit: mm



/ Marking Instructions



() / Temperature Profile for Dip Soldering(Pb-Free)



/ Resistance to Soldering Heat Test Conditions

/ Packaging SPEC.

封装形式	包装数量					包装尺寸		
	只 袋	袋 盒	只 盒	盒 箱	只 箱	袋	盒	箱

封装形式	包装数量					包装尺寸	
	只 纸带	纸带 盒	纸带层 盒	盒 箱	只 箱	盒	箱
							小箱 大箱

/ Notices